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Texas Instruments SN74LS280N

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SN54LS280, SN54S280, SN74LS280, SN74S280 9-BIT ODD/EVEN PARITY GENERATORS/CHECKERS

SDLS152 - DECEMBER 1972 - REVISED MARCH 1988

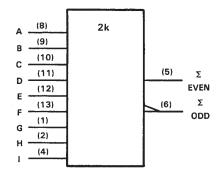
- Generates Either Odd or Even Parity for Nine Data Lines
- Cascadable for n-Bits
- Can Be Used to Upgrade Existing Systems using MSI Parity Circuits
- Typical Data-to-Output Delay of Only 14 ns for 'S280 and 33 ns for 'LS280
- Typical Power Dissipation: 'LS280...80 mW
 'S280...335 mW

FUNCTION TABLE

NUMBER OF INPUTS A	OUTPUTS					
THRUI THAT ARE HIGH	Σ EVEN	Σ ODD				
0, 2, 4, 6, 8	н	L				
1, 3, 5, 7, 9	L	н				

H = high level, L = low level

logic symbol[†]



[†]This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC

Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

description

These universal, monolithic, nine-bit parity generators/checkers utilize Schottky-clamped TTL high-performance circuitry and feature odd/even outputs to faciliate operation of either odd or even parity application. The word-length capability is easily expanded by cascading as shown under typical application data.

Series 54LS/74LS and Series 54S/74S parity generators/checkers offer the designer a trade-off between reduced power consumption and high performance. These devices can be used to upgrade the performance of most systems utilizing the '180 parity generator/checker. Although the 'LS280 and 'S280 are implemented without expander inputs, the corresponding function is provided by the availability of an input at pin 4 and the absence of any internal connection at pin 3. This permits the 'LS280 and 'S280 to be substituted for the '180 in existing designs to produce an identical function even if 'LS280's and 'S280's are mixed with existing '180's.

These devices are fully compatible with most other TTL circuits. All 'LS280 and 'S280 inputs are buffered to lower the drive requirements to one Series 54LS/74LS or Series 54S/74S standard load, respectively.

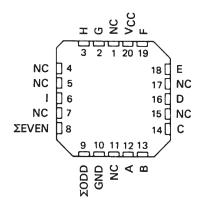
PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



1

SN54LS280, SN SN74LS280, SN											
(TOP VIEW)											
G H NC Ι ΣΕVEN ΣODD GND		U 14 13 12 11 10 9 8	VCC F D C B A								

SN54LS280, SN54S280 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

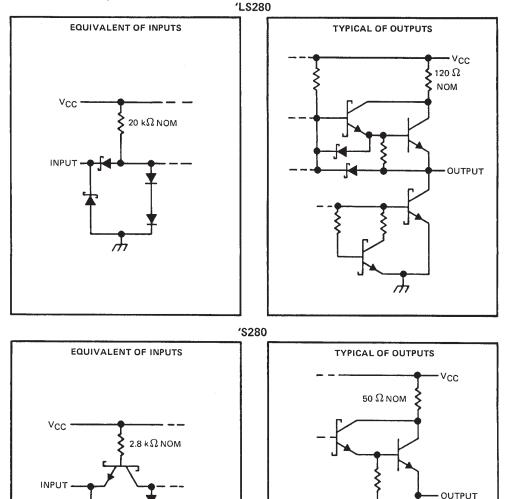


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schematics of inputs and outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

h

Input voltage: 'LS280		
Operating free-air temperature rang	e: SN54'	-55° C to 125°
	SN74'	
Storage temperature range		
TE 1: Voltage values are with respect to ne	twork ground terminal.	

d





SN54LS280, SN54S280, SN74LS280, SN74S280 9-BIT ODD/EVEN PARITY GENERATORS/CHECKERS

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recommended operating conditions

		SI	N54LS2	80	SI	UNIT		
		MIN	NOM	MAX	MIN	NOM	MAX	
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
v_{IH}	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.7			0.8	V
юн	High-level output current			- 0.4			- 0.4	mA
10L	Low-level output current			4			8	mA
TA	Operating free-air temperature	- 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS				80	SI	V74LS2	80	LINUT
				MIN	түр‡	MAX	MIN	TYP‡	MAX	UNIT
VIK	$V_{CC} = MIN,$	l _l = – 18 mA				- 1.5			- 1.5	V
V _{OH}	V _{CC} = MIN, V _{IL} = MAX,	V _{IH} = 2 V, I _{OH} = - 0.4 m	۱A	2.5	3.4		2.7	3.4		v
VOL	V _{CC} = MIN, V _{IL} = MAX	V _{IH} = 2 V,	$I_{OL} = 4 \text{ mA}$ $I_{OL} = 8 \text{ mA}$		0.25	0.4		0.25	0.4	v
L L	V _{CC} = MAX,	V1 = 7 V				0.1			0.1	mA
ін	V _{CC} = MAX,	VI = 2.7 V	· · · · · · · · · · · · · · · · · · ·			20		····	20	μΑ
ЦL	V _{CC} = MAX,	VI = 0.4 V				- 0.4			- 0.4	mA
los§	V _{CC} = MAX			- 20		- 100	- 20		100	mA
lcc	V _{CC} = MAX,	See Note 2			16	27		16	27	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

 \ddagger All typical values are at V_{CC} = 5 V, T_A = 25°C. §Not more than one output should be shorted at a time and duration of the short circuit should not exceed one second.

NOTE 2: I_{CC} is measured with all inputs grounded and all outputs open.

switching characteristics, $V_{CC} = 5 V$, $T_A = 25^{\circ}C$

PARAMETER¶	FROM (INPUT)	TO TEST CONDITIONS		MIN	түр	MAX	UNIT
^t PLH	Data	Σ Even			33	50	
^t PHL	Dala	2 Even	$C_L = 15 \text{ pF}, R_L = 2 \text{ k}\Omega,$		29	45	ns
^t PLH	Data	Σ Odd	 Inputs not under test at 0 V, See Note 3 		23	35	
^t PHL	5813	- Odd	366 NOTE 3		31	50	ns

¶tpLH = propagation delay time, low-to-high-level output; tpHL = propagation delay time, high-to-low-level output NOTE 3: Load circuits and voltage waveforms are shown in Section 1.





SN54LS280, SN54S280, SN74LS280, SN74S280 9-BIT ODD/EVEN PARITY GENERATORS/CHECKERS

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recommended operating conditions

	S	N54S28	30	S	UNIT		
	MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V _{CC}	4.5	5	5.5	4.75	5	5.25	V
High-level output current, IOH			1			-1	mA
Low-level output current, IOL			20			20	mA
Operating free-air temperature, T _A	55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CONDITION	IS [†]	MIN	ТҮР‡	MAX	UNIT
VIH	High-level input voltage			2			V
VIL	Low-level input voltage	·····				0.8	v
VIK	Input clamp voltage	V _{CC} = MIN, I _I = -18 mA				1.2	V
Vон	High-level output voltage	$V_{CC} = MIN, V_{IH} = 2V,$	SN54S'	2.5	3.4		
·04		VIL = 0.8 V, 10H = -1 mA	SN74S'	2.7	3.4		V
Vol	Low-level output voltage	$V_{CC} = MIN, V_{IH} = 2V,$				0.5	V
UL		VIL = 0.8 V, IOL = 20 mA				0.5	ľ
Ц	Input current at maximum input voltage	V _{CC} = MAX, V _I = 5.5 V				1	mA
ЧН	High-level input current	V _{CC} = MAX, V ₁ = 2.7 V				50	μA
ΊL	Low-level input current	V _{CC} = MAX, V _I = 0.5 V				-2	mA
los	Short-circuit output current§	V _{CC} = MAX		-40		-100	mA
		Var - MAX Sar Nata D	SN54S280		67	99	-
Icc	Supply current	V _{CC} = MAX, See Note 2	SN74S280	67		105	mA
		$V_{CC} = MAX, T_A = 125^{\circ}C,$ See Note 2	SN54S280N			94	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

[‡]All typical values are at V_{CC} = 5 V, T_A = 25°C.

Not more than one output should be shorted at a time and duration of the short circuit should not exceed one second.

NOTE 2: I_{CC} is measured with all inputs grounded and all outputs open.

switching characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER¶	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	ТҮР	MAX	UNIT
^t PLH	Data	Σ Even			14	21	
^t PHL	Data	2 Even	$C_{L} = 15 pF, R_{L} = 280 \Omega,$		11.5	18	ns
^t PLH	Data	ΣOdd	See Note 3		14	21	
tPHL	Data	2 Odu			11.5	18	ns

 $f_{tPLH} = propagation delay time, low-to-high-level output: t_{PHL} = propagation delay time, high-to-low-level output NOTE 3: Load circuits and voltage waveforms are shown in Section 1.$



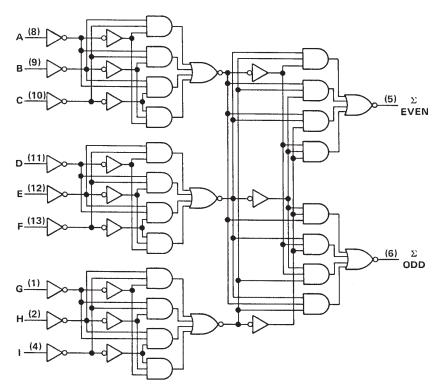


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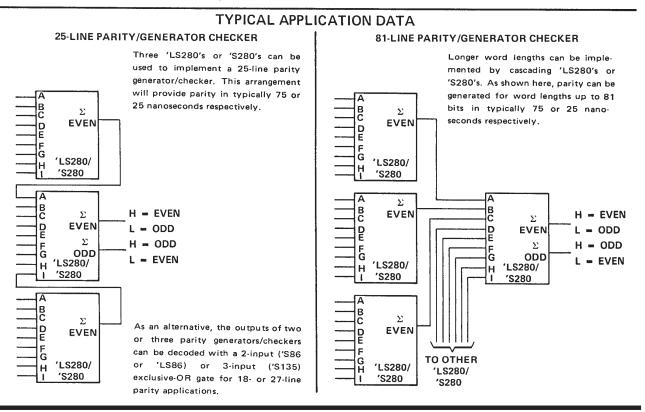
SN54LS280, SN54S280, SN74LS280, SN74S280 9-BIT ODD/EVEN PARITY GENERATORS/CHECKERS

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logic diagram (positive logic)



Pin numbers shown are for D, J, N, and W packages.







17-Dec-2015

PACKAGING INFORMATION

Orderable Device	Status	Package Type		Pins		Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Sampl
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
JM38510/32901BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32901BCA	Sampl
M38510/32901BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32901BCA	Samp
M38510/32901BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32901BCA	Samp
SN54LS280J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS280J	Samp
SN54LS280J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS280J	Samp
SN54S280J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54S280J	Samp
SN54S280J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54S280J	Samp
SN74LS280D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS280	Samp
SN74LS280D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS280	Samp
SN74LS280J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	0 to 70		
SN74LS280J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	0 to 70		
SN74LS280N	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS280N	Samj
SN74LS280N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS280N	Samj
SN74LS280N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN74LS280N3	OBSOLETE	E PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN74LS280NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS280	Samj
SN74LS280NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS280	Samj
SN74S280D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	0 to 70		
SN74S280D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	0 to 70		
SN74S280N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70	SN74S280N	
SN74S280N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70	SN74S280N	

Addendum-Page 1



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Lead/Ball Finish MSL Peak Temp Device Marking Orderable Device Status Package Type Package Pins Package Eco Plan Op Temp (°C) Samples Drawing Qty (1) (2) (6) (3) (4/5) SN74S280N3 OBSOLETE PDIP TBD Call TI Call TI 0 to 70 Ν 14 SN74S280N3 OBSOLETE Call TI PDIP Ν 14 TBD Call TI 0 to 70 SNJ54LS280J ACTIVE CDIP J 14 1 TBD A42 N / A for Pkg Type -55 to 125 SNJ54LS280J Samples SNJ54LS280J ACTIVE CDIP .1 14 1 TBD A42 N / A for Pkg Type -55 to 125 SNJ54LS280J Samples SNJ54LS280W ACTIVE CFP w 14 1 TBD A42 N / A for Pkg Type -55 to 125 SNJ54LS280W Samples SNJ54I S280W SN.1541 S280W ACTIVE CFP w 14 1 TBD A42 N / A for Pkg Type -55 to 125 Samples SNJ54S280J ACTIVE CDIP 14 TBD A42 N / A for Pkg Type -55 to 125 SNJ54S280J J 1 Samples SNJ54S280J ACTIVE CDIF J 14 1 TBD A42 N / A for Pkg Type SNJ54S280J -55 to 125 Samples SNJ54S280W ACTIVE CFP W TBD A42 N / A for Pkg Type -55 to 125 SNJ54S280W 14 1 Sample SNJ54S280W ACTIVE CFP w 14 1 TBD A42 N / A for Pkg Type -55 to 125 SNJ54S280W

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs. LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design. PREVIEW: Device has been announced but is not in production. Samples may or may not be available. OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined. Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS Compatible) as defined above. Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight is between the die and package).

in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device

Addendum-Page 2

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(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "--" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54LS280, SN54S280, SN74LS280, SN74S280 :

• Catalog: SN74LS280, SN74S280

• Military: SN54LS280, SN54S280

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications





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TEXAS INSTRUMENTS

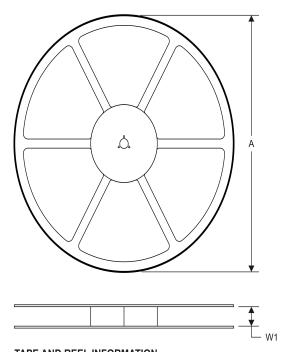
PACKAGE MATERIALS INFORMATION

14-Jul-2012

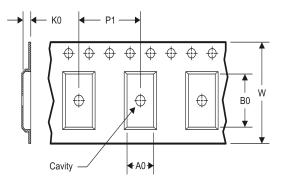
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TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
w	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS280NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1



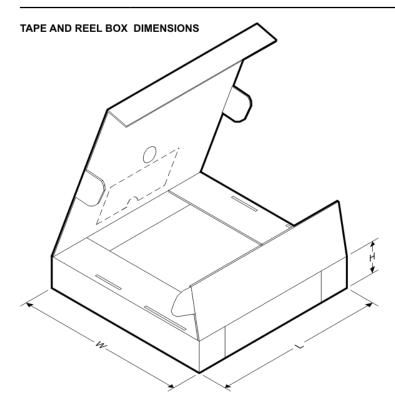
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14-Jul-2012



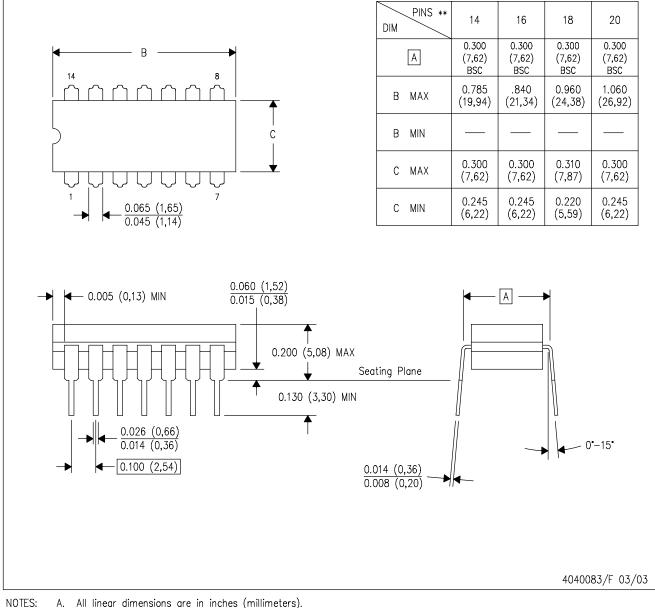
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS280NSR	SO	NS	14	2000	367.0	367.0	38.0



J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



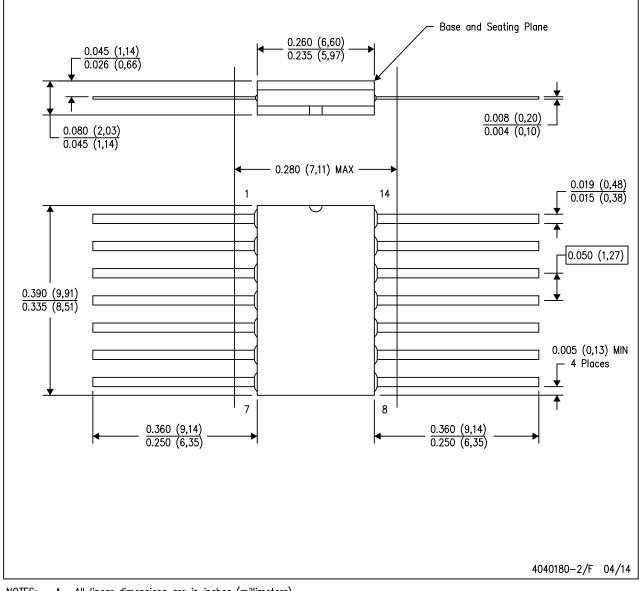
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.



MECHANICAL DATA

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



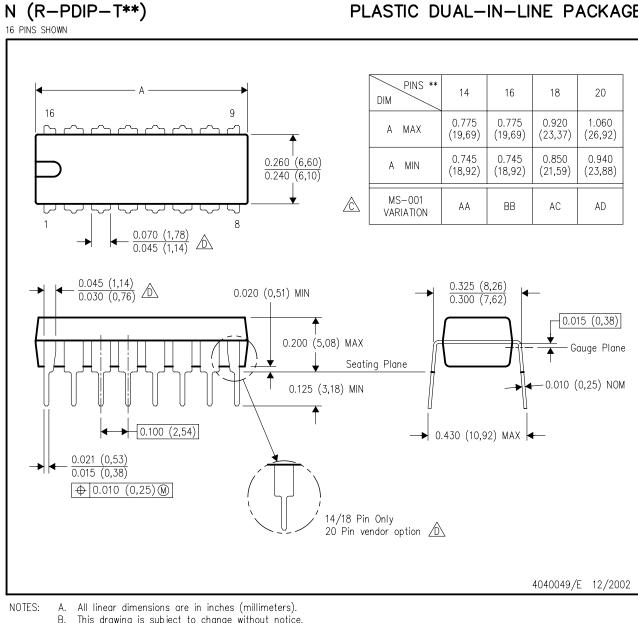
NOTES:

- All linear dimensions are in inches (millimeters). Α.
- Β. This drawing is subject to change without notice. This package can be hermetically sealed with a ceramic lid using glass frit. C.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14





MECHANICAL DATA



PLASTIC DUAL-IN-LINE PACKAGE

This drawing is subject to change without notice.

🖄 Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).

The 20 pin end lead shoulder width is a vendor option, either half or full width.

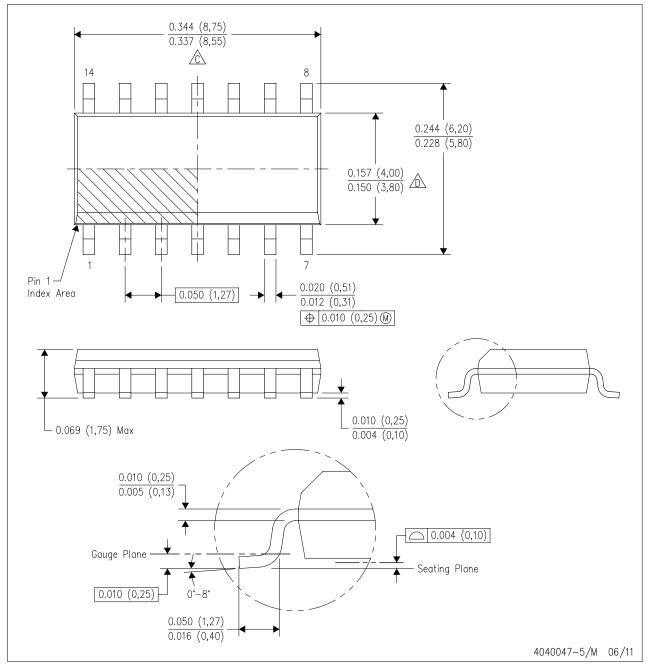




MECHANICAL DATA

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES:

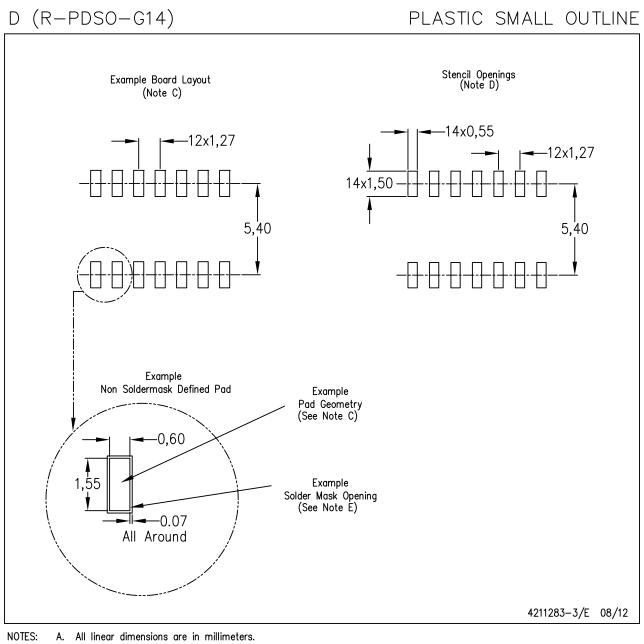
A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.





LAND PATTERN DATA



- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

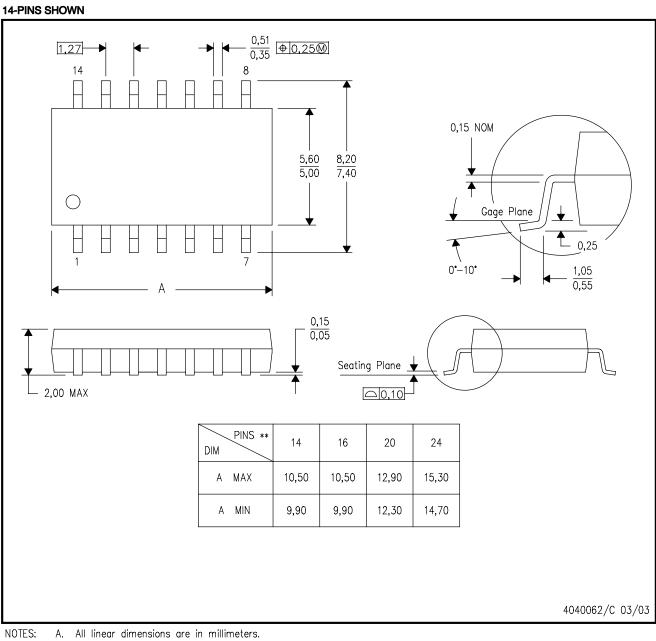




NS (R-PDSO-G**)

MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE



B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.





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Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

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